



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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Part Number: APB3025ESGC-F01

High Efficiency Red  
Super Bright Green

### Features

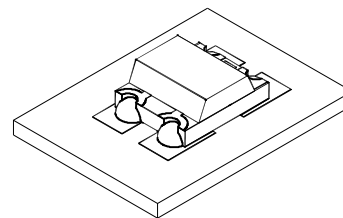
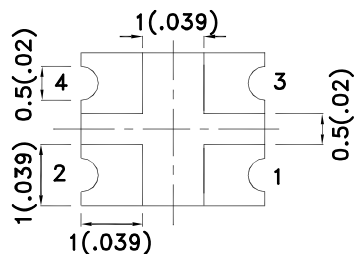
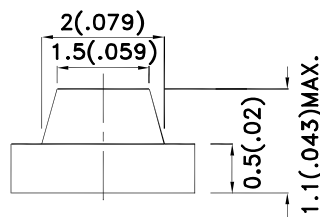
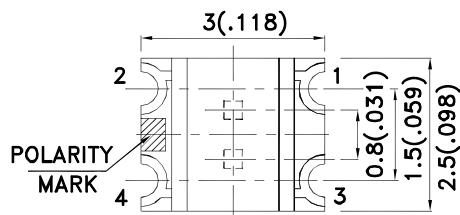
- 3.0mmx2.5mm SMT LED, 1.1mm thickness.
- Bi-color, Low power consumption.
- Wide viewing angle.
- Ideal for backlight and indicator.
- Package : 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

### Description

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

The Super Bright Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

### Package Dimensions



#### Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.2(0.008)$  unless otherwise noted.
3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
4. The device has a single mounting surface. The device must be mounted according to the specifications.



## Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
APB3025ESGC-F01	High Efficiency Red (GaAsP/GaP)	WATER CLEAR	8	15	120°
	Super Bright Green (GaP)		8	15	

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity/ luminous Flux: +/-15%.

## Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	High Efficiency Red Super Bright Green	627 565		nm	IF=20mA
λD [1]	Dominant Wavelength	High Efficiency Red Super Bright Green	625 568		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	High Efficiency Red Super Bright Green	45 30		nm	IF=20mA
C	Capacitance	High Efficiency Red Super Bright Green	15 15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	High Efficiency Red Super Bright Green	2 2.2	2.5 2.5	V	IF=20mA
IR	Reverse Current	High Efficiency Red Super Bright Green		10 10	uA	VR = 5V

Notes:

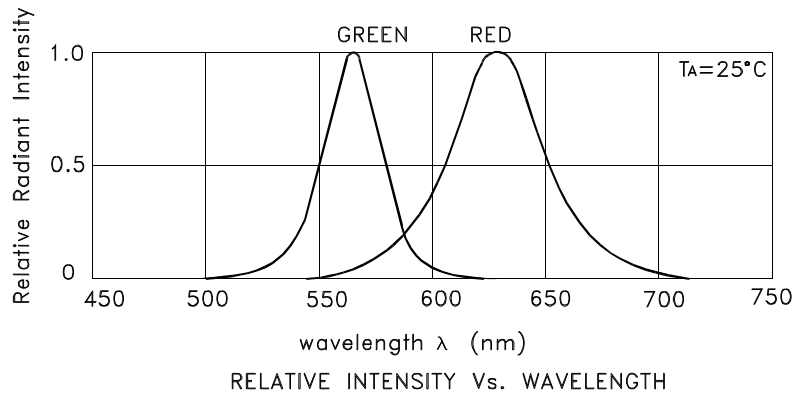
1. Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.

## Absolute Maximum Ratings at TA=25°C

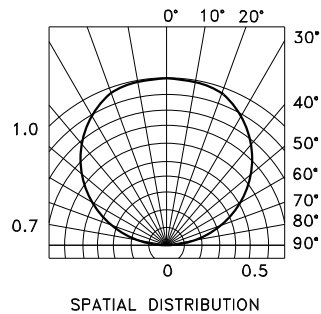
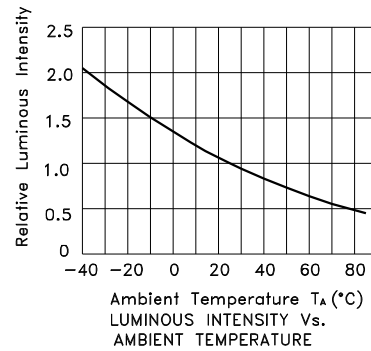
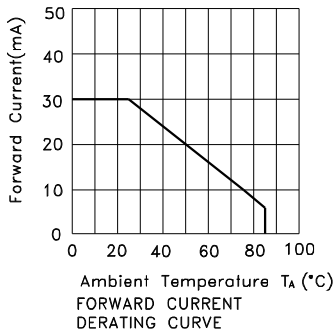
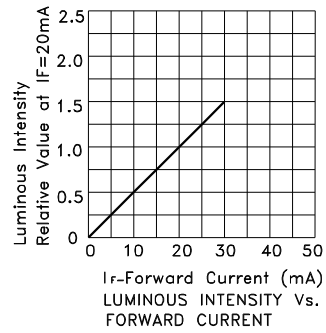
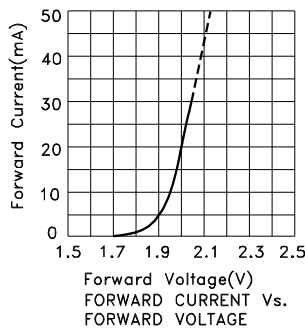
Parameter	High Efficiency Red	Super Bright Green	Units
Power dissipation	75	62.5	mW
DC Forward Current	30	25	mA
Peak Forward Current [1]	160	140	mA
Reverse Voltage	5		V
Operating Temperature	-40°C To +85°C		
Storage Temperature	-40°C To +85°C		

Note:

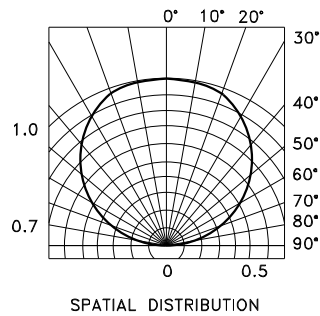
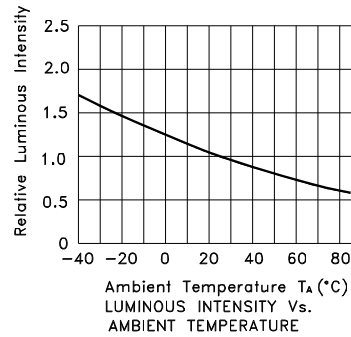
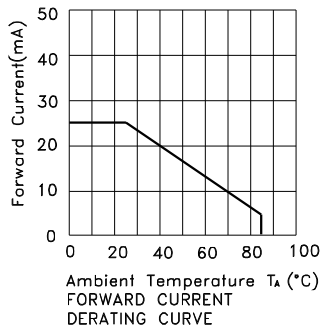
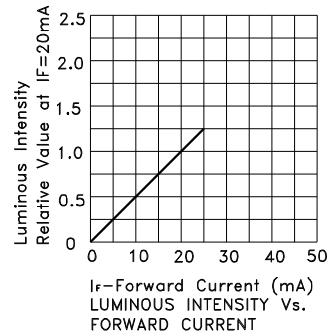
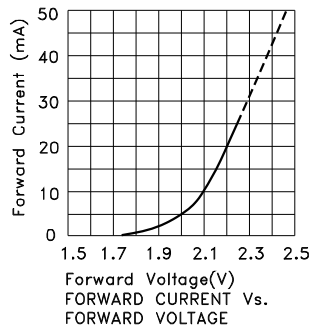
1. 1/10 Duty Cycle, 0.1ms Pulse Width.



## APB3025ESGC-F01 High Efficiency Red



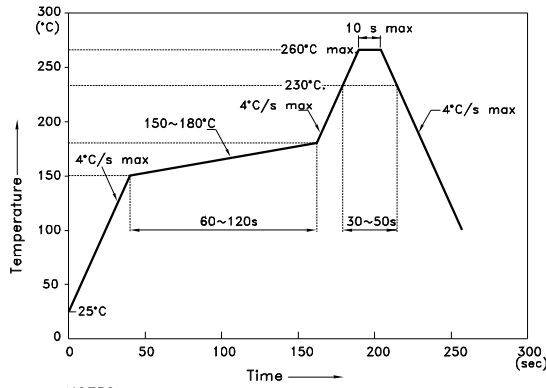
## Super Bright Green



## APB3025ESGC-F01

Reflow soldering is recommended and the soldering profile is shown below.  
Other soldering methods are not recommended as they might cause damage to the product.

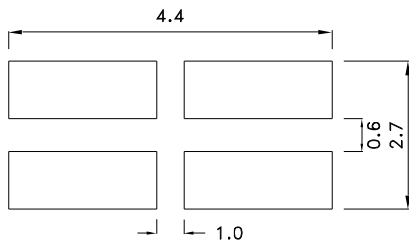
Reflow Soldering Profile For Lead-free SMT Process.



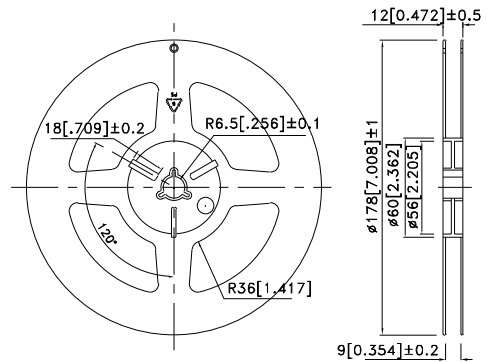
NOTES:

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

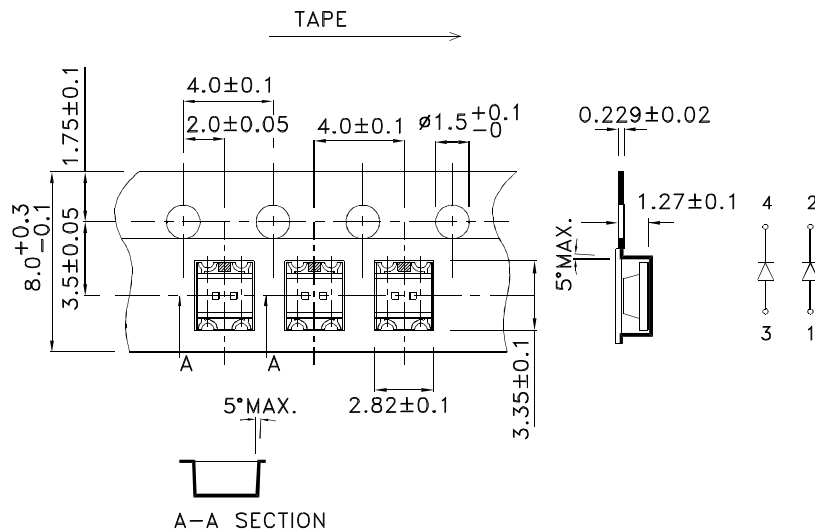
### Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



### Reel Dimension



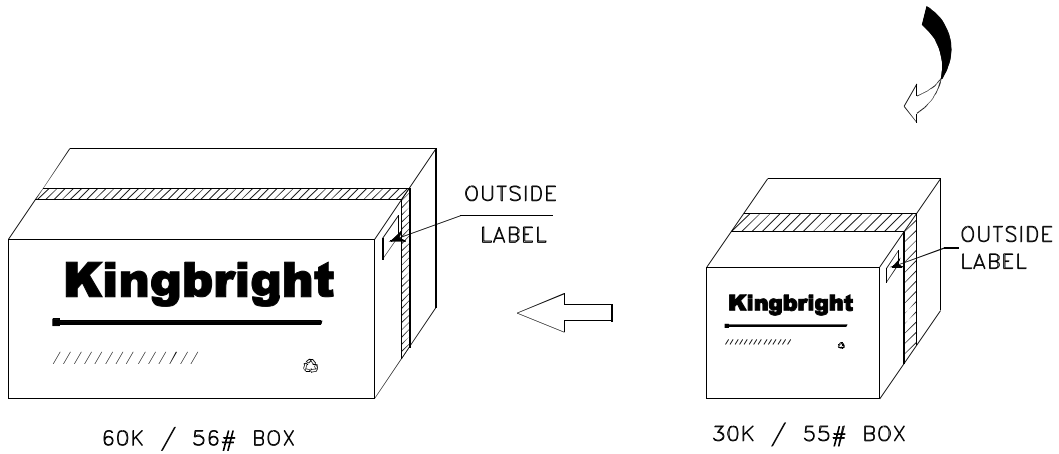
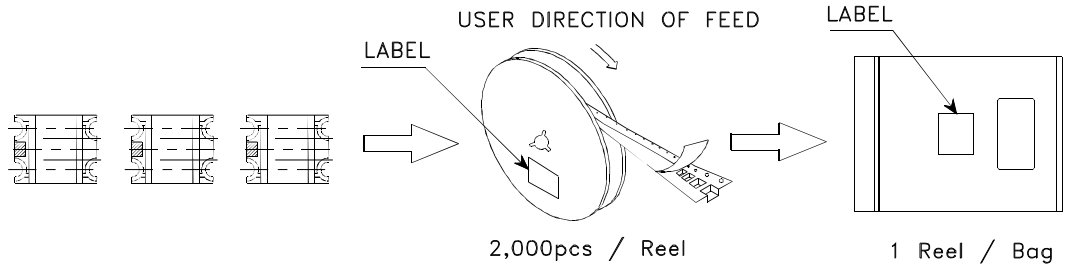
### Tape Dimensions (Units : mm)




# Kingbright

## PACKING & LABEL SPECIFICATIONS

APB3025ESGC-F01



<h1>Kingbright</h1>		
P/NO: APB3025xxx		
QTY: 2,000 pcs	Q.C.	Q.C. xx xx xxxx PASSED
S/N: XXXX		
CODE: XXX		
LOT NO:		
 xxxxxxxxxxxxxxxxxxxxxxxx		
RoHS Compliant		